
Multiple Output MEMS PCIe Gen1/2/3/4 Clocks for Automotive

Features

- Automotive AEC-Q100 Qualified
- Complies with PCIe Gen1/2/3/4 Common Clock Spec
- Integrated MEMS Resonator Eliminates the Need for External 25 MHz Crystal
- Wide Temperature Range:
 - Automotive Grade 2: -40°C to +105°C
 - Automotive Grade 3: -40°C to +85°C
- 100 MHz HCSL/LVDS/LVCMOS Options Available
- Dedicated Output Enable (OE) Pins for Clock Outputs
- Small Footprints:
 - 14-Lead VQFN (DSA557-03, Two Outputs)
 - 20-Lead VQFN (DSA557-04, Three Outputs; DSA557-05, Four Outputs)
- Excellent Shock and Vibration Immunity
 - Qualified to MIL-STD-883
- High Reliability
 - 20x Better MTF than Quartz Oscillators
- Low Current Consumption: 30% Lower than Competing Devices
- Supply Range of 2.25V to 3.63V
- Lead-Free and RoHS Compliant

Applications

- Automotive Infotainment
- Automotive ADAS
- Autonomous Driving
- In-Vehicle Network

General Description

The DSA557 series of high performance PCI Express clock generators use a proven silicon MEMS technology to provide 100 MHz differential output clocks with excellent jitter and stability over a wide range of supply voltages and temperatures. By eliminating the need for quartz or SAW technology, MEMS oscillators significantly enhance reliability and accelerate product development, while meeting stringent clock performance criteria for a variety of communications, storage, and networking applications.

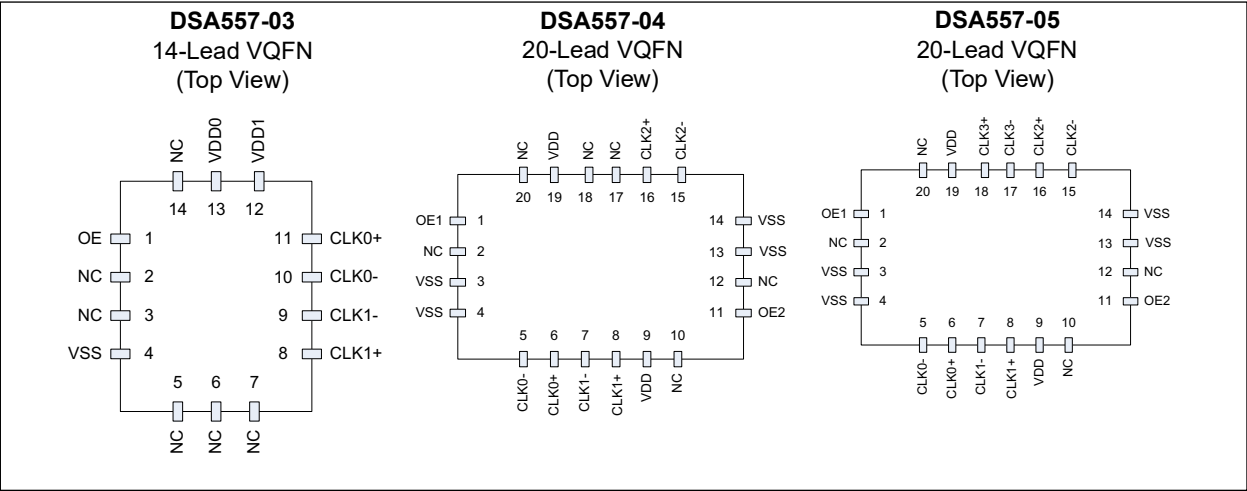
The DSA557-03/04/05 have two, three, and four 100 MHz outputs, respectively. All have output enable/disable features.

The DSA557-03 is available in a space-saving 14-lead VQFN package. The DSA557-04 and DSA557-05 are available in a 20-lead VQFN.

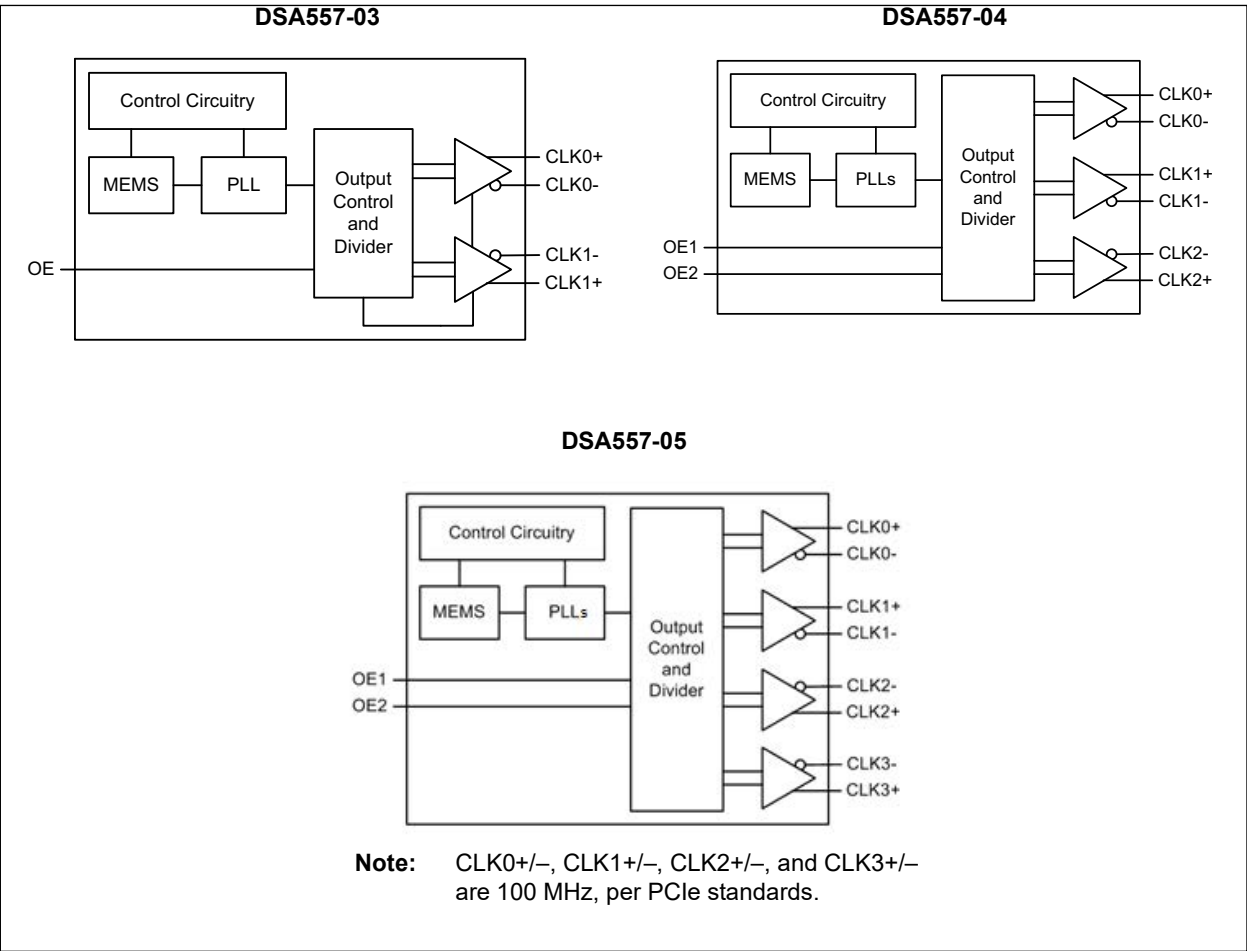
Additional LVDS and LVCMOS output formats are available in addition to the default HCSL output format.

DSA557-03/04/05

Package Types



Block Diagrams



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Input Voltage	–0.3V to $V_{DD} + 0.3V$
Supply Voltage	–0.3V to +4.0V
ESD Protection on All Pins (HBM)	4 kV
ESD Protection on All Pins (CDM)	1.5 kV

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

Electrical Characteristics: Unless otherwise specified, $T = +25^{\circ}C$, $V_{DD} = 3.3V$.						
Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Supply Voltage	V_{DD}	2.25	—	3.63	V	Note 1
Supply Current, DSA557-03	I_{DD}	—	21	23	mA	HCSL output, EN pin low, output disabled
		—	60	—		HCSL output, EN pin high, output enabled
Supply Current, DSA557-04	I_{DD}	—	42	46	mA	HCSL output, EN pin low, output disabled
		—	100	—		HCSL output, EN pin high, output enabled
Supply Current, DSA557-05	I_{DD}	—	42	46	mA	HCSL output, EN pin low, output disabled
		—	120	—		HCSL output, EN pin high, output enabled
Frequency Stability (including frequency variations due to initial tolerance, temp., and power supply voltage)	Δf	—	—	± 100	ppm	All temperature ranges
		—	—	± 50		
Aging - 1st Year	Δf	—	—	± 5	ppm	± 1 ppm each subsequent year
Startup Time (Note 2)	t_{SU}	—	—	5	ms	$T = +25^{\circ}C$
Input Logic Levels						
Input Logic High	V_{IH}	$0.75 \times V_{DD}$	—	—	V	—
Input Logic Low	V_{IL}	—	—	$0.25 \times V_{DD}$	V	—
Output Disable Time (Note 3)	t_{DS}	—	—	5	ns	—
Output Enable Time	t_{EN}	—	—	20	ns	—
Enable Pull-Up Resistor (Note 4)	—	—	40	—	k Ω	Internally pulled up
HCSL Outputs (Note 5)						
Output Logic High	V_{OH}	0.725	—	—	V	$R_L = 50\Omega$
Output Logic Low	V_{OL}	—	—	0.1	V	$R_L = 50\Omega$
Peak-to-Peak Output Swing	—	—	750	—	mV	Single-Ended
Output Frequency	f_{OUT}	—	100	—	MHz	—

ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Characteristics: Unless otherwise specified, T = +25°C, V _{DD} = 3.3V.						
Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Output Transition Time (Note 6)	t _r /t _f	200	—	400	ps	20% to 80%, R _L = 50Ω, C _L = 2 pF
Output Duty Cycle	SYM	48	—	52	%	Differential
Period Jitter (Note 7)	J _{PER}	—	2.5	—	ps _{RMS}	f ₀₁ = f ₀₂ = 100 MHz
Jitter, Phase (Common Clock Architecture)	T _J	—	17	86	ps _{PP}	PCIe Gen 1.1, (Note 8) T _J = D _J + 14.069 x R _J (BER 10 ⁻¹²)
	J _{RMS-CCHF}	—	1.46	3.1	ps _{RMS}	PCIe Gen 2.1, 1.5 MHz to Nyquist, (Note 8)
	J _{RMS-CCLF}	—	0.08	3.0	ps _{RMS}	PCIe Gen 2.1, 10 kHz to 1.5 MHz, (Note 8)
	J _{RMS-CC}	—	0.313	1.0	ps _{RMS}	PCIe Gen 3.0, (Note 8)
	J _{RMS-CC}	—	0.313	0.5	ps _{RMS}	PCIe Gen 4.0, 16 GHz, (Note 8)
Integrated Phase Noise (Data Clock Architecture)	J _{RMS-DCHF}	—	2.15	4.0	ps _{RMS}	PCIe Gen 2.1, 1.5 MHz to Nyquist, (Note 8)
	J _{RMS-DCLF}	—	0.06	7.5	ps _{RMS}	PCIe Gen 2.1, 10 kHz to 1.5 MHz, (Note 8)
	J _{RMS-DC}	—	0.32	1.0	ps _{RMS}	PCIe Gen 3.0, (Note 8)
LVDS Output						
Offset Voltage	V _{OS}	1.125	1.25	1.40	V	V _{DD} = 2.5V/3.3V
V _{OS} Magnitude Change	ΔV _{OS}	—	—	50	mV	—
Output High Voltage	V _{OH}	0.9xV _{DD}	—	—	V	—
Output Low Voltage	V _{OL}	—	—	0.1xV _{DD}	V	—
Output Frequency	f _{OUT}	—	100	—	MHz	—
Differential Output Voltage	V _{OD}	275	350	475	mV _{PP}	—
V _{OD} Magnitude Change	ΔV _{OD}	—	—	40	mV	—
LVDS Output Rise/Fall Time	t _r /t _f	—	200	—	ps	20% – 80%
Output Duty Cycle	ODC	48	50	52	%	20% – 80%, R _L = 50Ω, C _L = 2 pF
Period Jitter, Peak to Peak	J _{PTP}	—	2.5	—	ps	f _{OUT} = 100 MHz, Standard Drive
Integrated Phase Noise	J _{PH}	—	0.28	—	ps _{RMS}	200 kHz to 20 MHz @ 100 MHz, T _A = +105°C
		—	0.4	—		100 kHz to 80 MHz @ 100 MHz
		—	1.7	2.0		12 kHz to 10 MHz @ 100 MHz

ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Characteristics: Unless otherwise specified, T = +25°C, V _{DD} = 3.3V.						
Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
LVC MOS Output						
Output High Voltage	V _{OH}	0.8xV _{DD}	—	—	V	±10 mA drive current
Output Low Voltage	V _{OL}	—	—	0.2xV _{DD}	V	±10 mA drive current
Output Frequency	f _{OUT}	—	100	—	MHz	—
Output Rise/Fall Time	t _r /t _f	—	1.2	—	ns	20% – 80%, C _L = 15 pF
Output Duty Cycle	ODC	48	50	52	%	f _{OUT} = 100 MHz, Standard Drive
Period Jitter	J _{PTP}	—	3	—	ps _{RMS}	f _{OUT} = 100 MHz, Standard Drive
Integrated Phase Noise	J _{PH}	—	0.3	—	ps _{RMS}	200 kHz to 20 MHz @ 100 MHz
		—	0.38	—		100 kHz to 20 MHz @ 100 MHz
		—	1.7	2.0		12 kHz to 20 MHz @ 100 MHz

- Note 1:** Each pin V_{DD} should be filtered with a 0.1 µF capacitor.
- 2:** t_{SU} is time to 100 ppm of output frequency after V_{DD} is applied and outputs are enabled.
- 3:** Output Waveform and Test Circuit figures define the parameters.
- 4:** Output is enabled if pad is floated or not connected.
- 5:** Contact Microchip for alternate output options (LVDS, LVC MOS).
- 6:** Output Waveform and Connection Diagram define the parameters.
- 7:** Period Jitter includes crosstalk from adjacent output.
- 8:** Jitter limits established by Gen 1.1, Gen 2.1, Gen 3.0, and Gen 4.0 PCIe standards.

TEMPERATURE SPECIFICATIONS

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Temperature Ranges						
Operating Temperature Range	T _A	–40	—	+85	°C	Ordering Option I
		–40	—	+105	°C	Ordering Option L
Junction Operating Temperature	T _J	—	—	+150	°C	—
Storage Temperature Range	T _S	–55	—	+150	°C	—
Lead Temperature	—	—	+260	—	°C	Soldering, 40s

TABLE 2-2: DSA557-04 VQFN-20 PIN FUNCTION TABLE

Pin Number	Pin Name	Pin Type	Description
1	OE1	I	Output enable, active-high. Controls CLK0.
2	NC	N/A	Leave unconnected or grounded.
3	VSS	P	Ground.
4	VSS	P	Ground.
5	CLK0–	O	Complement output of differential pair.
6	CLK0+	O	True output of differential pair.
7	CLK1–	O	Complement output of differential pair.
8	CLK1+	O	True output of differential pair.
9	VDD	P	Power supply.
10	NC	N/A	Leave unconnected or grounded.
11	OE2	I	Output enable, active-high. Controls CLK1 and CLK2.
12	NC	N/A	Leave unconnected or grounded.
13	VSS	P	Ground.
14	VSS	P	Ground.
15	CLK2–	O	Complement output of differential pair.
16	CLK2+	O	True output of differential pair.
17	NC	N/A	Leave unconnected or grounded.
18	NC	N/A	Leave unconnected or grounded.
19	VDD	P	Power supply.
20	NC	N/A	Leave unconnected or grounded.

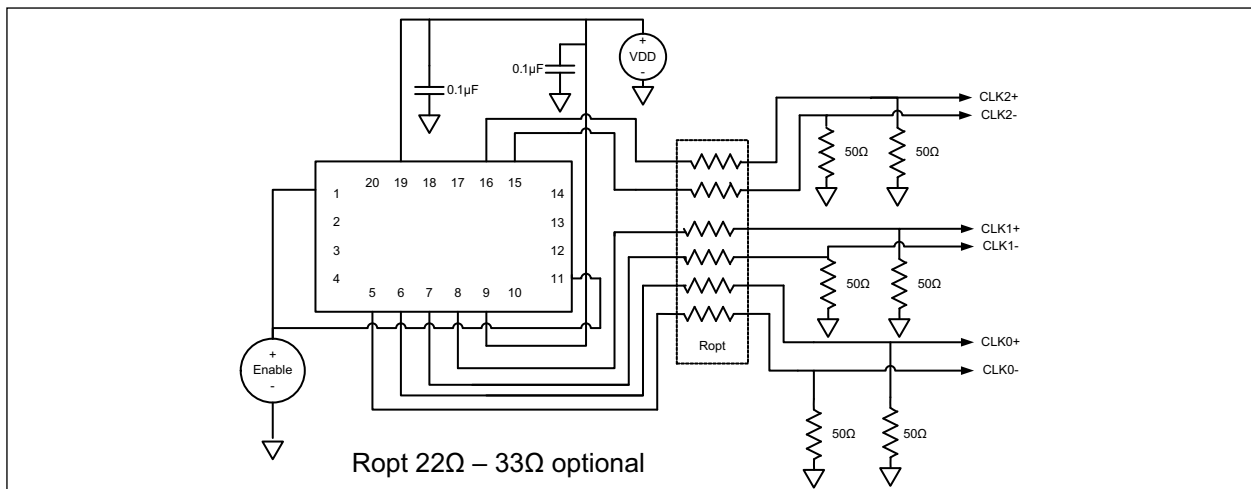


FIGURE 2-4: 20-Lead VQFN Connection Diagram with Three HCSL Outputs.

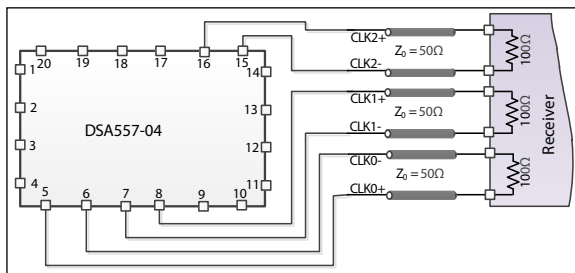


FIGURE 2-5: LVDS Outputs.

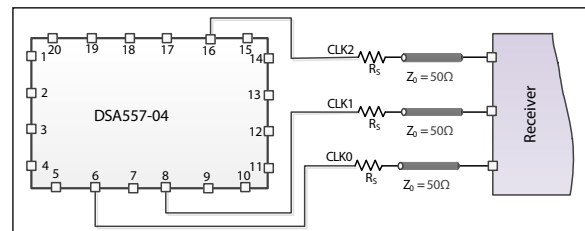


FIGURE 2-6: LVCMOS Outputs.

Pin Number	Pin Name	Pin Type	Description
1	OE1	I	Output enable, active-high. Controls CLK0 and CLK3.
2	NC	N/A	Leave unconnected or grounded.
3	VSS	P	Ground.
4	VSS	P	Ground.
5	CLK0–	O	Complement output of differential pair.
6	CLK0+	O	True output of differential pair.
7	CLK1–	O	Complement output of differential pair.
8	CLK1+	O	True output of differential pair.
9	VDD	P	Power supply.
10	NC	N/A	Leave unconnected or grounded.
11	OE2	I	Output enable, active-high. Controls CLK1 and CLK2.
12	NC	N/A	Leave unconnected or grounded.
13	VSS	P	Ground.
14	VSS	P	Ground.
15	CLK2–	O	Complement output of differential pair.
16	CLK2+	O	True output of differential pair.
17	CLK3–	O	Complement output of differential pair.
18	CLK3+	O	True output of differential pair.
19	VDD	P	Power supply.
20	NC	N/A	Leave unconnected or grounded.

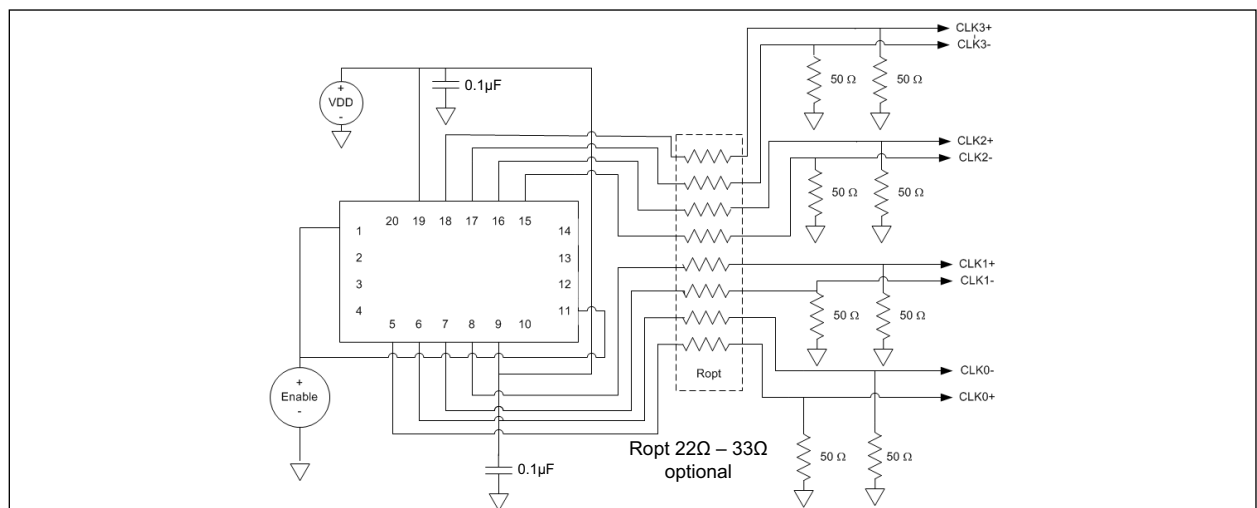


FIGURE 2-7: 20-Lead VQFN Connection Diagram with Four HCSL Outputs.

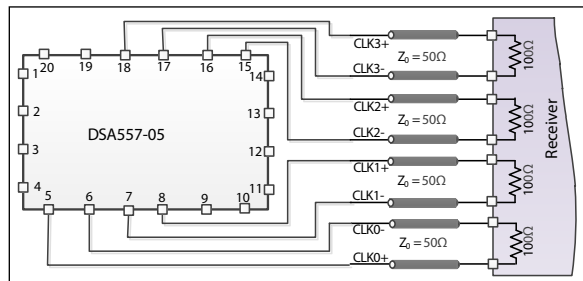


FIGURE 2-8: LVDS Outputs.

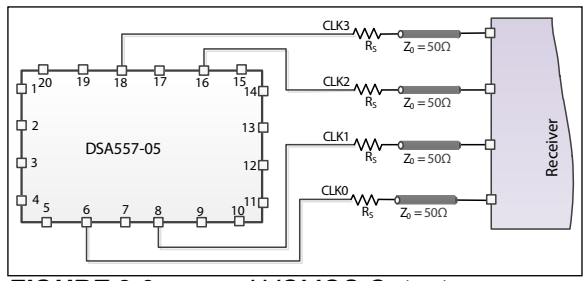


FIGURE 2-9: *LVC MOS Outputs.*

3.0 OUTPUT WAVEFORM

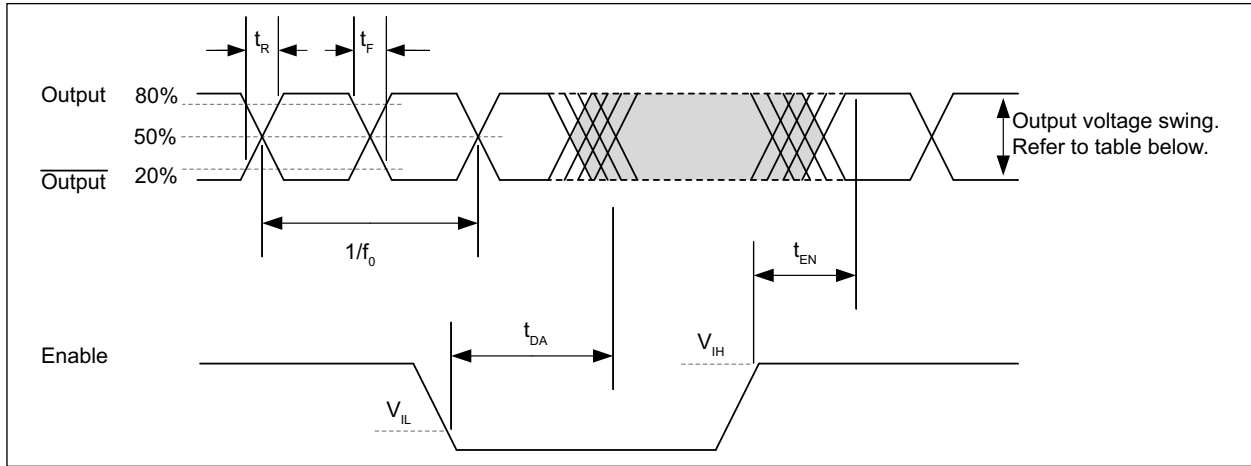


FIGURE 3-1: DSA557-03/04/05 Output Waveform.

TABLE 3-1: OUTPUT VOLTAGE SWING

Specification	V_{CM}	V_{SWING_SE} (typ.)
LVDS	1.2V	350 mV
HCSL	350 mV	675 mV

4.0 SOLDER REFLOW PROFILE

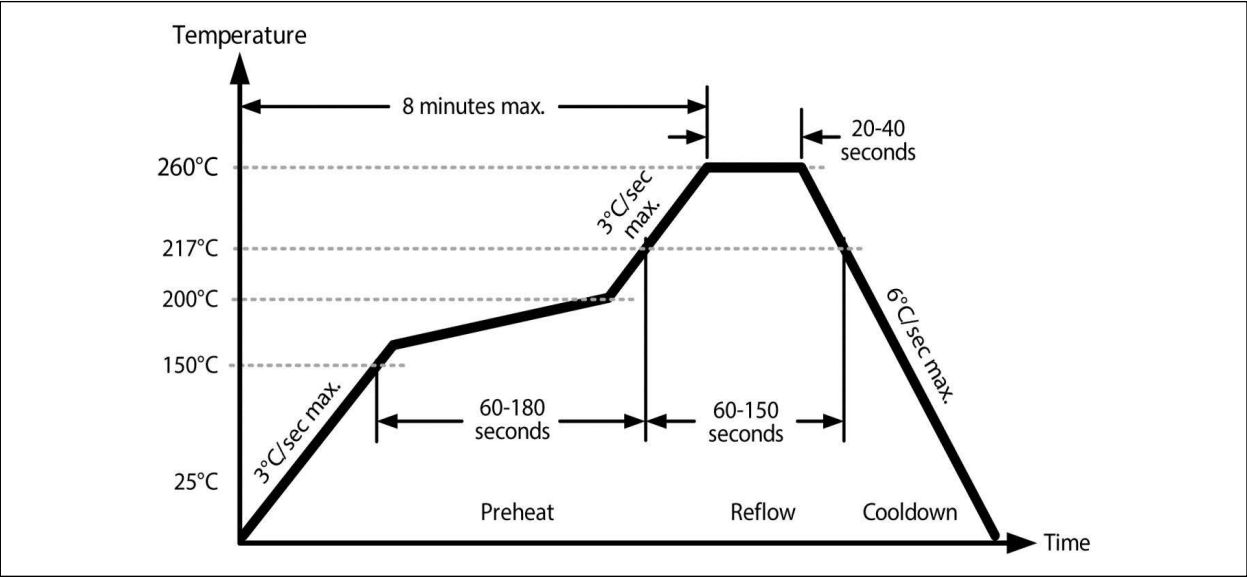


FIGURE 4-1: Solder Reflow Profile.

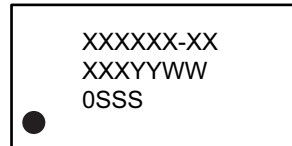
TABLE 4-1: SOLDER REFLOW

VQFN-14 MSL 1 @ 260°C Refer to JSTD-020C	
Ramp-Up Rate (200°C to Peak Temp.)	3°C/sec. max.
Preheat Time 150°C to 200°C	60 to 180 sec.
Time Maintained above 217°C	60 to 150 sec.
Peak Temperature	255°C to 260°C
Time within 5°C of Actual Peak	20 to 40 sec.
Ramp-Down Rate	6°C/sec. max.
Time 25°C to Peak Temperature	8 minutes max.

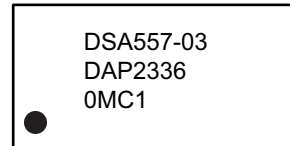
5.0 PACKAGING INFORMATION

5.1 Package Marking Information

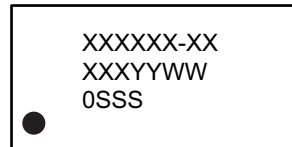
14-Lead VQFN*



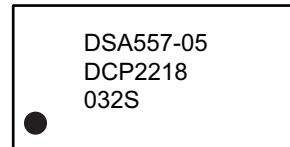
Example



20-Lead VQFN*



Example

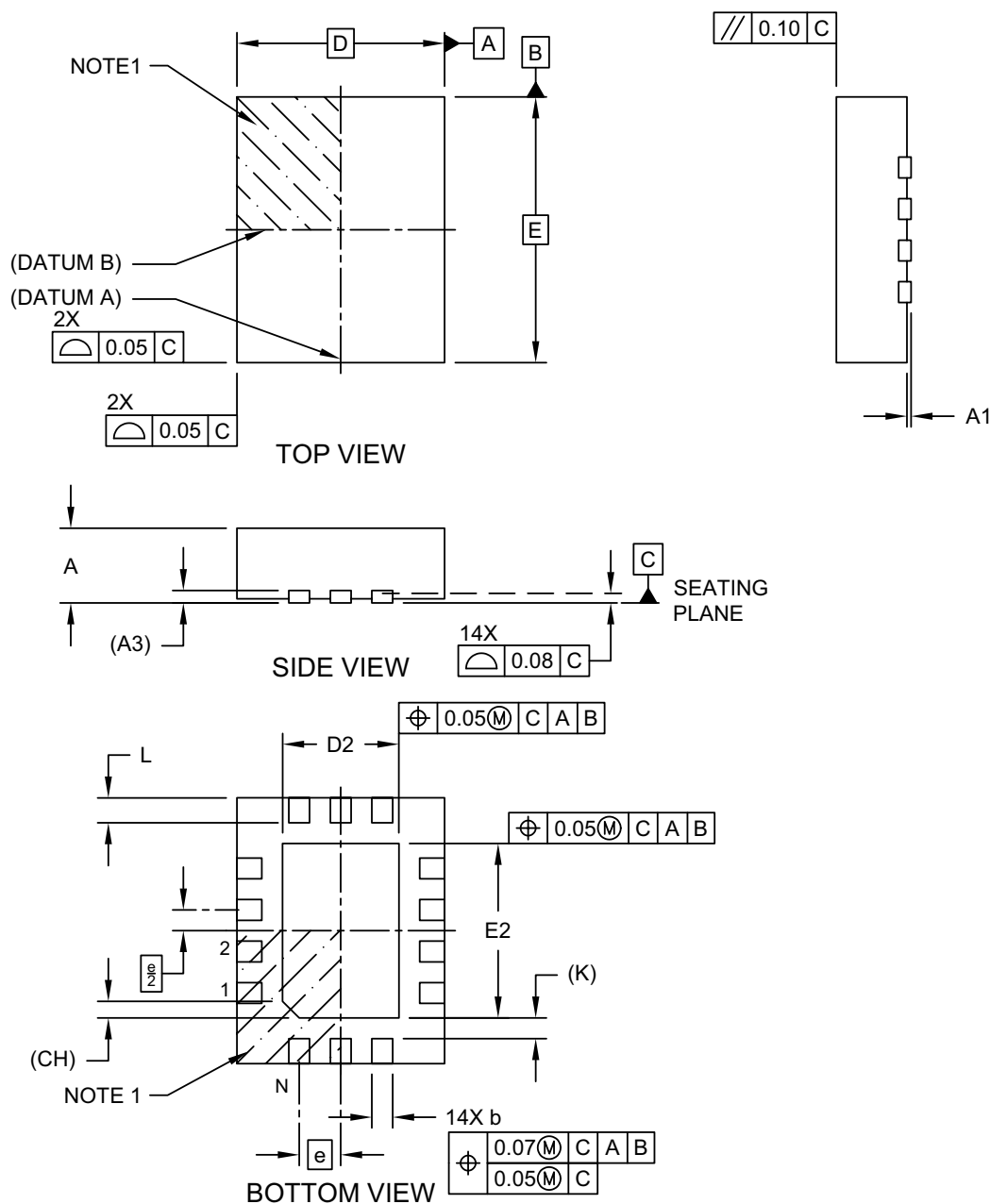


Legend: XX...X Product code
Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')
SSS Alphanumeric traceability code
(e3) Pb-free JEDEC® designator for Matte Tin (Sn)
* This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
•, ▲, ▼ Pin one index is identified by a dot, delta up, or delta down (triangle mark).

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.
Underbar (_) and/or Overbar (¯) symbol may not be to scale.

14-Lead Very Thin Plastic Quad Flat, No Lead Package (MUA) - 2.5x3.2x0.9 mm Body [VQFN] With 1.4x2.1 mm Exposed Pad; Micrel Legacy Package

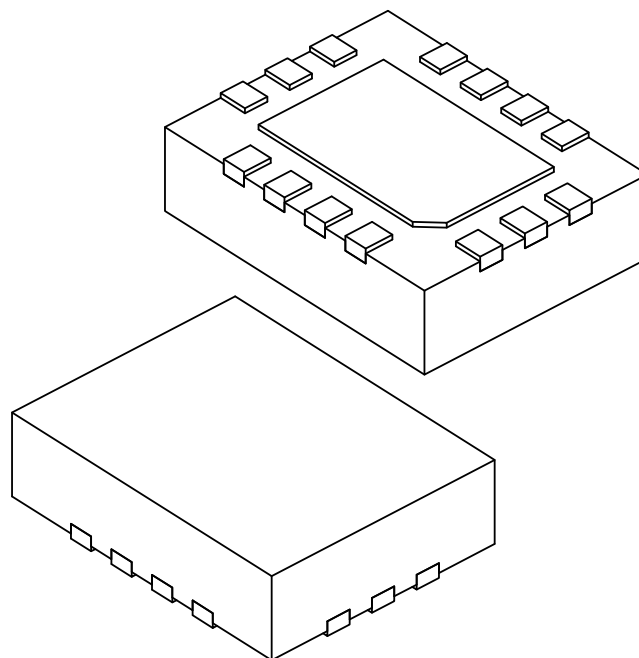
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-1098-MUA Rev B Sheet 1 of 2

14-Lead Very Thin Plastic Quad Flat, No Lead Package (MUA) - 2.5x3.2x0.9 mm Body [VQFN] With 1.4x2.1 mm Exposed Pad; Micrel Legacy Package

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N		14		
Pitch	e		0.50 BSC		
Overall Height	A		0.80	0.85	0.90
Standoff	A1		0.00	0.02	0.05
Terminal Thickness	A3		0.10 REF		
Overall Length	D		2.50 BSC		
Exposed Pad Length	D2		1.35	1.40	1.45
Overall Width	E		3.20 BSC		
Exposed Pad Width	E2		2.05	2.10	2.15
Exposed Pad Index Chamfer	CH		0.20 REF		
Terminal Width	b		0.20	0.25	0.30
Terminal Length	L		0.25	0.30	0.35
Terminal-to-Exposed-Pad	K		0.25 REF		

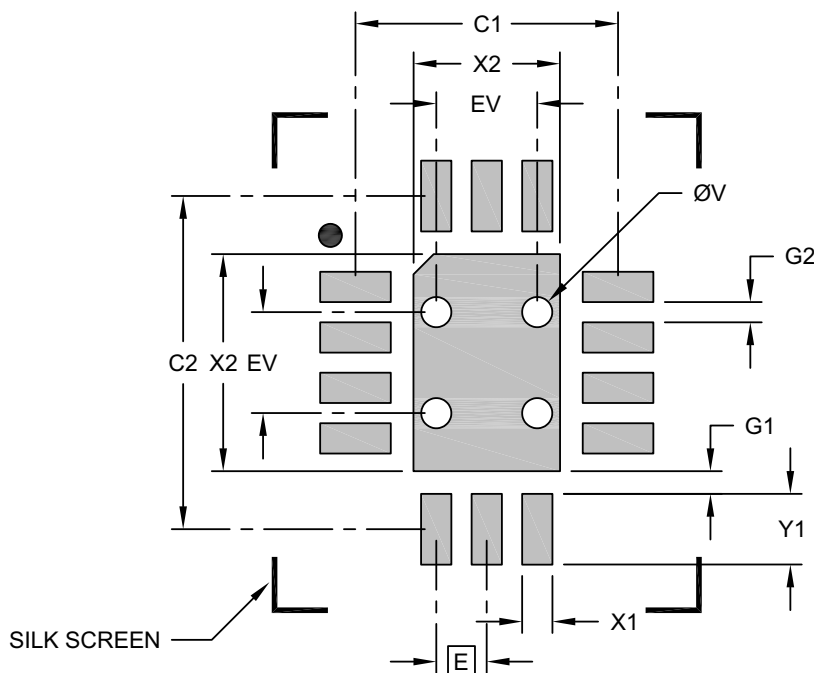
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1098-MUA Rev B Sheet 2 of 2

14-Lead Very Thin Plastic Quad Flat, No Lead Package (MUA) - 2.5x3.2x0.9 mm Body [VQFN] With 1.4x2.1 mm Exposed Pad; Micrel Legacy Package

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Center Pad Width	X2			1.45
Center Pad Length	Y2			2.15
Contact Pad Spacing	C1		2.60	
Contact Pad Spacing	C2		3.30	
Contact Pad Width (X14)	X1			0.30
Contact Pad Length (X14)	Y1			0.70
Contact Pad to Center Pad (X14)	G1	0.23		
Contact Pad to Contact Pad (X10)	G2	0.20		
Thermal Via Diameter	V		0.30	
Thermal Via Pitch	EV		1.00	

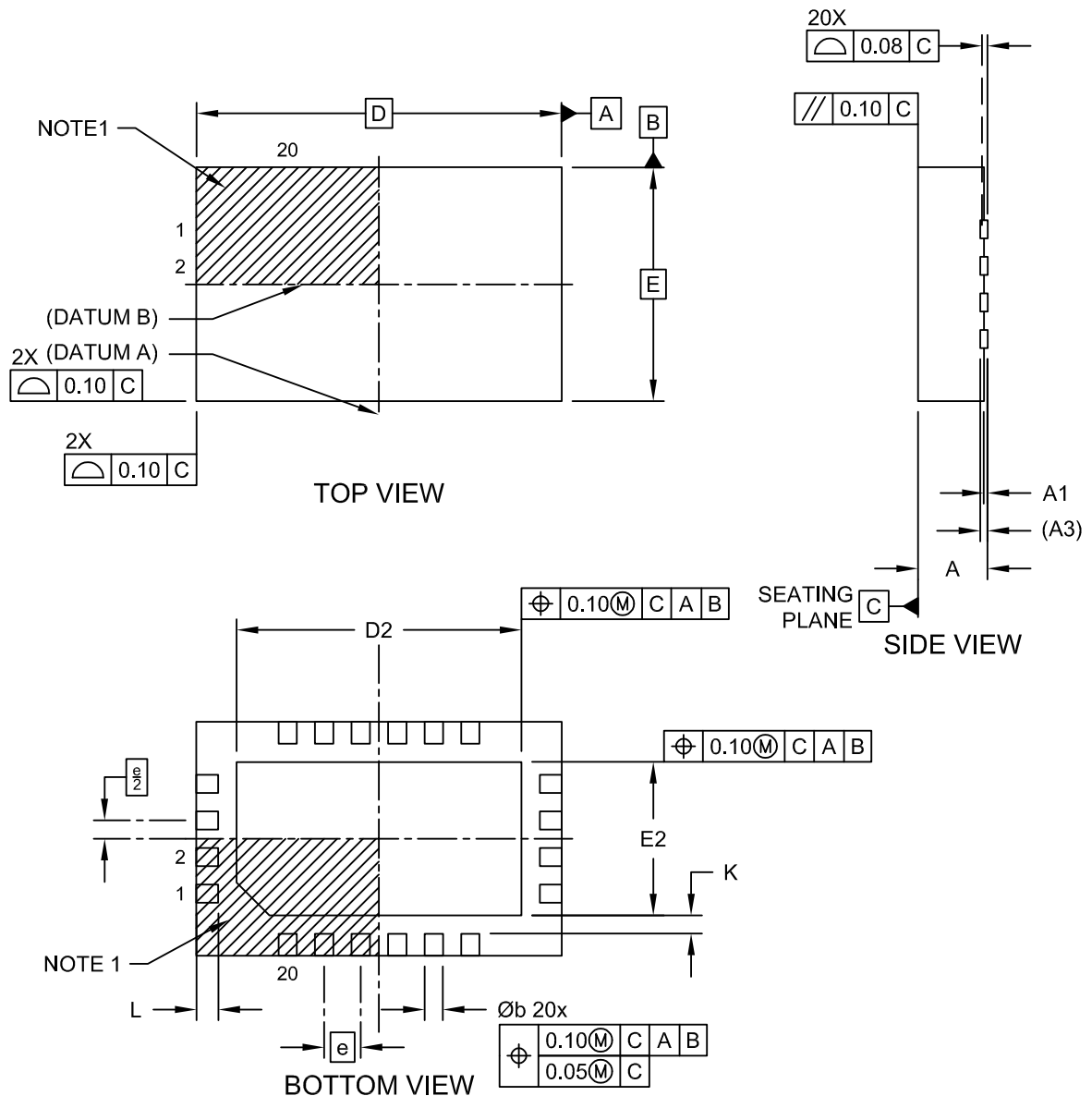
Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-3098-MUA Rev B

20-Lead Very Thin Plastic Quad Flat, No Lead Package (P9A) - 5.0x3.2x0.9 mm Body [VQFN] With 3.9x2.1 Exposed Pad

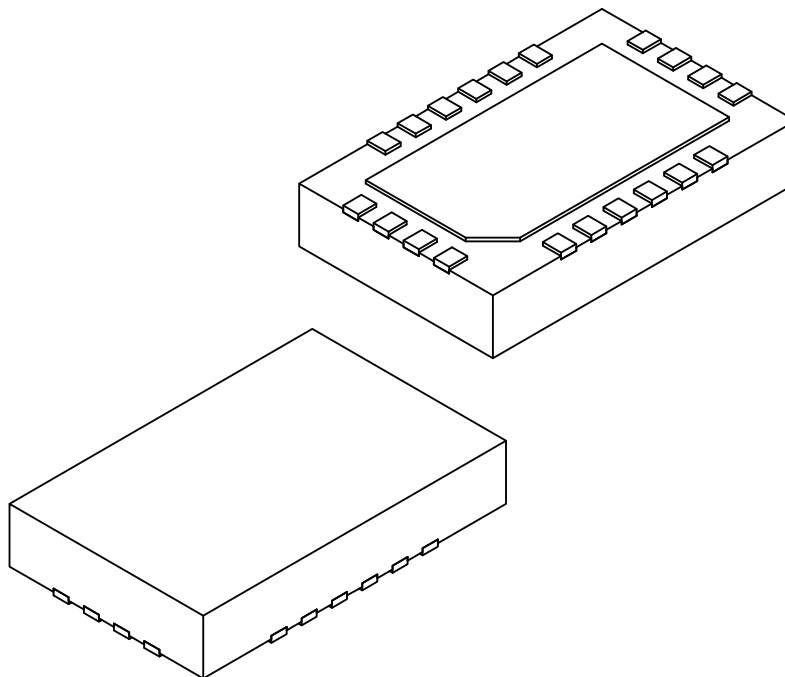
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-1117 Rev A Sheet 1 of 2

20-Lead Very Thin Plastic Quad Flat, No Lead Package (P9A) - 5.0x3.2x0.9 mm Body [VQFN] With 3.9x2.1 Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	20		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.85	0.90
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.203 REF		
Overall Length	D	5.00 BSC		
Exposed Pad Length	D2	3.80	3.90	4.00
Overall Width	E	3.20 BSC		
Exposed Pad Width	E2	2.00	2.10	2.20
Terminal Width	b	0.20	0.25	0.30
Terminal Length	L	0.20	0.30	0.40
Terminal-to-Exposed-Pad	K	0.25 REF		

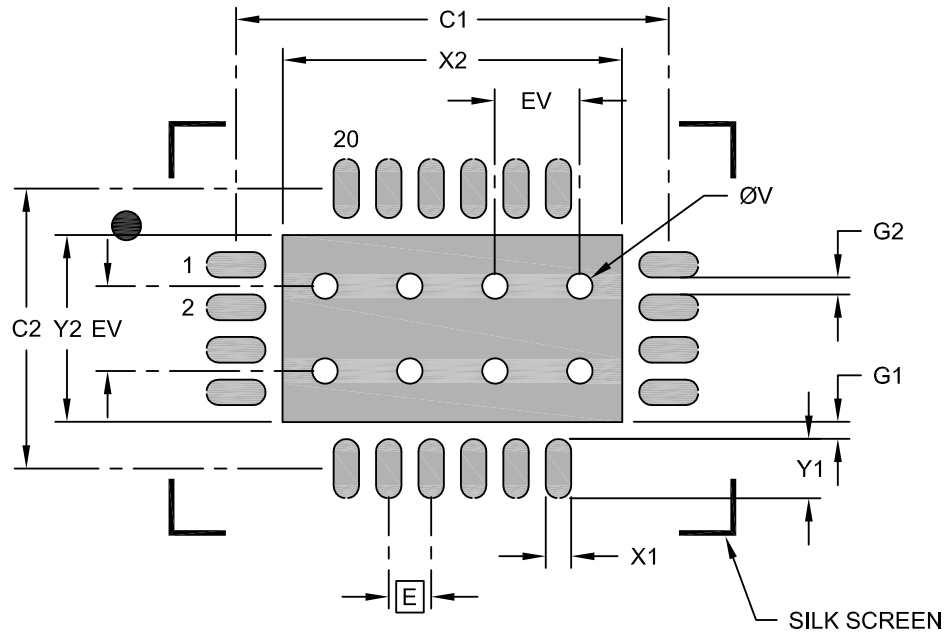
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1117 Rev A Sheet 2 of 2

20-Lead Very Thin Plastic Quad Flat, No Lead Package (P9A) - 5.0x3.2x0.9 mm Body [VQFN] With 3.9x2.1 Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	X2			4.00
Optional Center Pad Length	Y2			2.20
Contact Pad Spacing	C1		5.10	
Contact Pad Spacing	C2		3.30	
Contact Pad Width (X20)	X1			0.30
Contact Pad Length (X20)	Y1			0.70
Contact Pad to Center Pad (X20)	G1	0.20		
Contact Pad to Contact Pad (X16)	G2	0.20		
Thermal Via Diameter	V		0.30	
Thermal Via Pitch	EV		1.00	

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-3117 Rev A

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (April 2019)

- Initial release of DSA557-03/04/05 as Microchip data sheet DS20006175A.

Revision B (May 2020)

- Updated [Product Identification System](#) section to add the Automotive Suffix to the full part number.
- Removed LVPECL option throughout data sheet.
- Added LVDS and LVCMOS information to [Electrical Characteristics](#) section.
- Added [Figure 2-2](#), [Figure 2-3](#), [Figure 2-5](#), [Figure 2-6](#), [Figure 2-8](#), and [Figure 2-9](#).

Revision C (June 2020)

- Updated Phase Jitter values in the [Electrical Characteristics](#) table.

Revision D (July 2023)

- Updated descriptions for Pin 12 and Pin 13 in [Table 2-1](#).
- Updated all Package Outline Drawings.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART No.	XXXX	X	X	X	X	XXX	Examples:
Device	Output Format	Package	Temp. Range	Stability	Packing Option	Automotive Suffix	
Device: DSA557-03: Two Output PCIe Clock Generator for Automotive DSA557-04: Three Output PCIe Clock Generator for Automotive DSA557-05: Four Output PCIe Clock Generator for Automotive							a) DSA557-0344FL0VAO: Two HCSL Outputs PCIe Clock Generator for Automotive, 14-Lead VQFN, -40°C to +105°C Temperature Range, ±100 ppm Stability, 110/Tube, Standard Automotive b) DSA557-04111K1TVAO: Three LVCMOS Outputs PCIe Clock Generator for Automotive, 20-Lead VQFN, -40°C to +85°C Temperature Range, ±50 ppm Stability, 1000/Reel, Standard Automotive c) DSA557-053344KL0VAO: Four Output PCIe Clock Generator for Automotive, (CLK3/CLK2: LVDS, CLK1/CLK0: HCSL), 20-Lead VQFN, -40°C to +105°C Temperature Range, ±100 ppm Stability, 72/Tube, Standard Automotive
Output (Note 1)	Format:	1 = LVCMOS 3 = LVDS 4 = HCSL					
Package:		F = 14-Lead VQFN (DSA557-03 Only) K = 20-Lead VQFN (DSA557-04/05 Only)					
Temperature Range:		L = -40°C to +105°C (Automotive Grade 2) I = -40°C to +85°C (Automotive Grade 3)					
Stability:		0 = ±100 ppm 1 = ±50 ppm					
Packing Option:		<blank>= 72/Tube (DSA557-04/05) <blank>= 110/Tube (DSA557-03) T = 1000/Reel (All Package Options)					
Automotive Suffix:	Vxx	= Automotive suffix in which "xx" is assigned by Microchip. Default value is "AO" for standard automotive part.					
Note 1: The Output Format's arrangement is CLK3 to CLK0 (left-to-right) and may only have as many digits as that particular part allows. For example, DSA557-03 has two outputs; the part number example can only have two digits in that location. DSA557-04 can only have three and DSA557-05 can only have four.							Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

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